L Number	Hits	Search Text	DB	Time stamp
1	193095	(low adj k) sicn sic sioc (silicon adj4 (dioxide carbon (carbon adj nitride)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 09:00
2	1436474	semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 09:00
3	6788	silicon with (diffused diffusion duffusing diffuse) with (metal cupper cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 09:01
4	8283	(si silicon) with (diffused diffusion duffusing diffuse) with (metal cupper cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 09:33
5	2356	((low adj k) sicn sic sioc (silicon adj4 (dioxide carbon (carbon adj nitride)))) and semiconductor and ((si silicon) with (diffused diffusion duffusing diffuse) with (metal cupper cu))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 09:03
6	27783	diffusion with barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 09:04
7	1241	(((low adj k) sicn sic sioc (silicon adj4 (dioxide carbon (carbon adj nitride)))) and semiconductor and ((si silicon) with (diffused diffusion duffusing diffuse) with (metal cupper cu))) and (diffusion with barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 09:04
8	37526	(etch etching etched) with (stop stopper stopped stopping)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 09:05
9	400	((((low adj k) sicn sic sioc (silicon adj4 (dioxide carbon (carbon adj nitride)))) and semiconductor and ((si silicon) with (diffused diffusion duffusing diffuse) with (metal cupper cu))) and (diffusion with barrier)) and ((etch etching etched) with (stop stopper stopped stopping))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 09:05
10	1094	(si silicon) with (diffused diffusion duffusing diffuse) with (cupper cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 10:10
11	156	(((((low adj k) sicn sic sioc (silicon adj4 (dioxide carbon (carbon adj nitride)))) and semiconductor and ((si silicon) with (diffused diffusion duffusing diffuse) with (metal cupper cu))) and (diffusion with barrier)) and ((etch etching etched) with (stop stopper stopped stopping))) and ((si silicon) with (diffused diffusion duffusing diffuse) with (cupper cu))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 09:33
12	2685	(si silicon) with (diffused diffusion duffusing diffuse) with (copper cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 10:28

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13	247	((si silicon) with (diffused diffusion duffusing diffuse) with (copper cu)) and (((((low adj k) sicn sic sioc (silicon adj4 (dioxide carbon (carbon adj nitride)))) and semiconductor and ((si silicon) with (diffused diffusion duffusing diffuse) with (metal cupper cu))) and (diffusion with barrier)) and ((etch etching etched) with (stop stopper stopped stopping)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 10:11
14	91	(((si silicon) with (diffused diffusion duffusing diffuse) with (copper cu)) and (((((low adj k) sicn sic sioc (silicon adj4 (dioxide carbon (carbon adj nitride)))) and semiconductor and ((si silicon) with (diffused diffusion duffusing diffuse) with (metal cupper cu))) and (diffusion with barrier)) and ((etch etching etched) with (stop stopper stopped stopping)))) not ((((((low adj k) sicn sic sioc (silicon adj4 (dioxide carbon (carbon adj nitride)))) and semiconductor and ((si silicon) with (diffused diffusion duffusing diffuse) with (metal cupper cu))) and (diffusion with barrier)) and ((etch etching etched) with (stop stopper stopped stopping))) and ((si silicon) with (diffused diffusion duffusing diffuse) with (cupper cu)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 10:12
15	75	(si silicon) adj2 (diffused diffusion duffusing diffuse) adj2 (copper cu)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 10:29
16	57	((si silicon) adj2 (diffused diffusion duffusing diffuse) adj2 (copper cu)) and ((low adj k) sicn sic sioc (silicon adj4 (dioxide carbon (carbon adj nitride)))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/11/02 10:30